Product Brief

Thermal Interface Material (TIM)

With the ongoing increase of power densities in power electronics the thermal interface between power module and heatsink becomes a larger challenge.

A thermal interface material, especially developed for and pre-applied to Infineon's power modules outperforms the general purpose materials available.

TIM not only provides the lowest thermal resistance, it also fulfills the highest quality standards given for power modules to achieve the longest lifetime and highest system reliability.

TIM has been developed to fit to most of our existing power module packages as well as to upcoming future designs. Using modules with preapplied TIM will achieve a reproducible thermal performance of power electronic applications.

Main Features

- Best in class thermal resistance
- Pre-applied to Infineon Modules
- Dry to the touch
- Optimized for dedicated Infineon Modules

Benefits

- Reduced process time in manufacturing
- Simplified mounting
- Increased system reliability
- Increased system lifetime
- Optimized thermal management
- Improved handling in case of maintenance

Applications

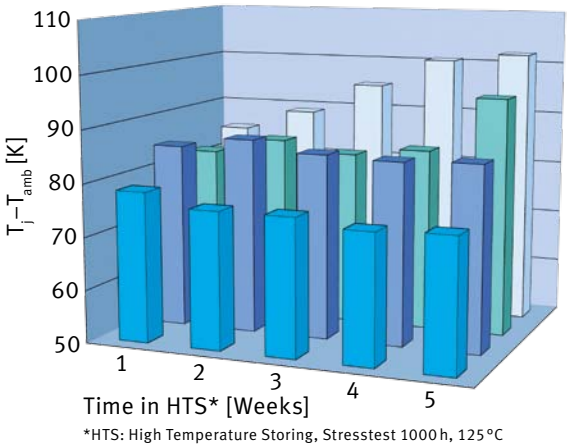
- Predestined for demanding applications in respect to lifetime and durability

www.infineon.com/tim

Pre-Applied Thermal Interface Material

The only Infineon-qualified solution

Thermal Improvement and Long-Term Stability



*HTS: High Temperature Storing, Stresstest 1000 h, 125 °C

- Mod-3: Material with gradual degradation
- Mod-2: Material with unexpected degradation
- Mod-1: Stable behavior as demanded
- IFX-TIM with superior performance

First module available:

- **EconoPACK™ +**

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